

MMSZ4702

General Description

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the leadless package.

Features

- · Compact surface mount with same footprint as mini-melf
- 500mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16kV) per Human Body Model

Ordering

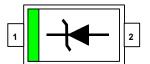
• 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

Absolute Maximum Ratings (note 1) T_A=25°C unless otherwise noted

Symbol	Parameter	Value	Units
T _{STG}	Storage Temperature	-55 ~ 150	°C
T _J	Maximum Junction Temperature	-55 ~ 150	°C
P_D	Total Power Dissipation at 25°C Derate above 25°C	500 6.7	mW mW/°C
R_{QJA}	Thermal Resistance Junction to Ambient	340	°C/W
R _{QJA}	Thermal Resistance Junction to Lead	150	°C/W
ΔV_{Z}	Maximum Voltage Change (Note 2)	150	mV
Lead Solder Temperature (Max 10 second duration)		260	°C
Nominal Zener Voltage (V _Z) at 50μA		15.0	V

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired. Note 2: Voltage change is equal to the difference between V_Z at $100\mu A$ and V_Z at $10\mu A$.

Top Mark: DM 1: Cathode 2: Anode



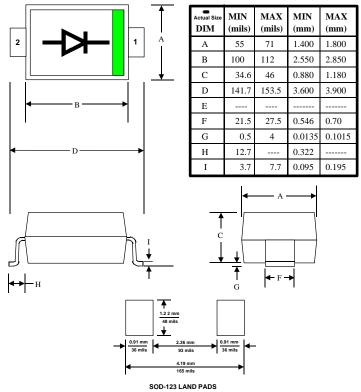
Electrical Characteristics T_A=25°C unless otherwise noted

Symbol	Characteristics	Test Conditions	Min.	Max.	Units
V_Z	Zener Voltage	$I_{ZT} = 50\mu A_{D.C}$	14.25	15.75	V
I _R	Reverse Leakage	V _R = 11.4V		50	nA
V _F	Forward Voltage	I _F = 10mA		900	mV
ΔV_Z	Delta Zener Voltage (Note 2)	I _{ZT} = 100μA to 10μA		150	mV

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SOD-123 PACKAGE PACKAGE CODE = (D6) Fairchild Semiconductor's Criteria





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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition	
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Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.	
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